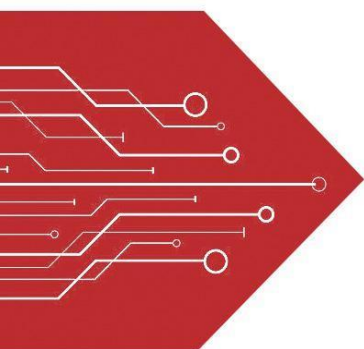
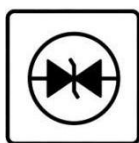


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

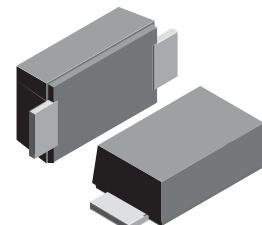


PLED

Product data sheet

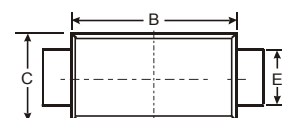
Features

- For surface mounted applications
- Low profile package
- Low incremental surge resistance, excellent clamping capability
- 200W peak pulse power capability with a 10/1000 μ s wave from, repetition rate (duty cycle): 0.01%
- High temperature soldering guaranteed: 260 °C/10 seconds, at terminals



Mechanical Data

- Case: JEDEC SOD-123FL, molded plastic over passivated chip
- Polarity: Color band denotes positive end (cathode) except for bidirectional
- Mounting position: Any
- Weight: 0.006 ounces, 0.02 gram



SOD-123FL

Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Maximum P_{PK} Dissipation (PW - 10/1000 μ s)	P_{PK}	200	W
Maximum P_{PK} Dissipation @ $T_A = 25^\circ\text{C}$ (PW - 8/10 μ s) (Note 2)	P_{PK}	1000	W
DC Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 3)	P_D	385	mW
Derate above 25°C		4.0	mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient (Note 3)	$R_{\theta JA}$	325	$^\circ\text{C/W}$
Thermal Resistance, Junction to Lead (Note 3)	$R_{\theta JL}$	26	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Notes :

- (1) Non-repetitive current pulse at $T_A = 25^\circ\text{C}$, per waveform of Fig. 2.
- (2) Non-repetitive current pulse at $T_A = 25^\circ\text{C}$, per waveform of Fig. 5.
- (3) Mounted with recommended minimum pad size, DC board FR4.

TYPE	Marking	Reverse Stand-Off voltage V_{RWM} (V)	Breakdown Voltage Min. @ I_T $V_{BR MIN}$ (V)	Breakdown Voltage Max. @ I_T $V_{BR MAX}$ (V)	Test Current I_T (mA)	Reverse Leakage @ V_{RWM} I_R (uA)	Maximum Clamping Voltage @ I_{PP} V_C (V)	Peak Pulse Current I_{PP} (mA)
PDCV300JB-MS	JK	30	33.3	36.8	1.0	1.0	48.4	4.1

FIG.1 - PULSE DERATING CURVE

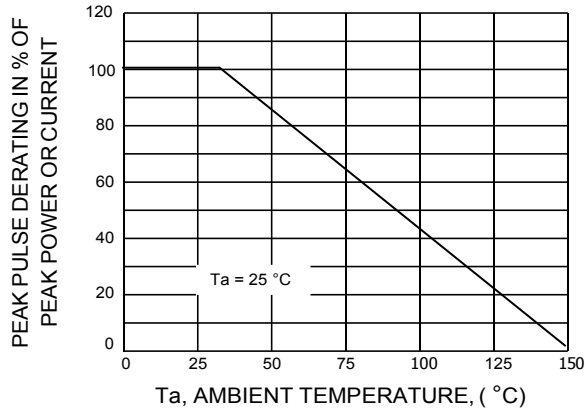


FIG.2 - 10 x 1000 μs PULSE WAVEFORM

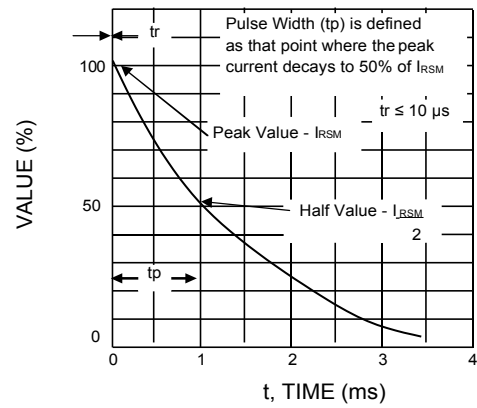


FIG.3 - STEADY STATE POWER DERATING

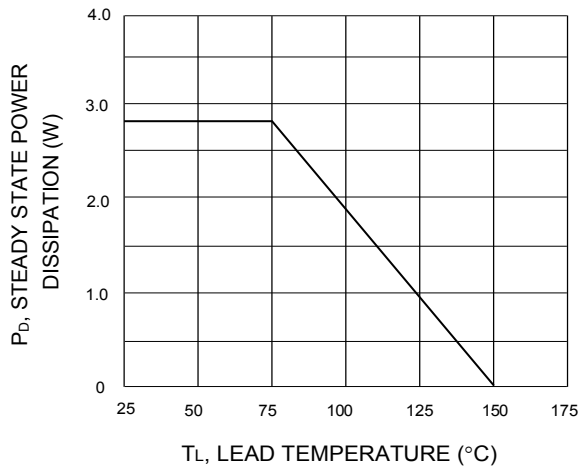


FIG.4 - PULSE RATING CURVE

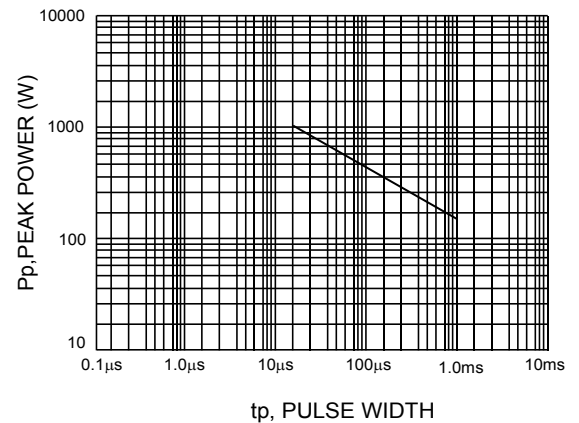
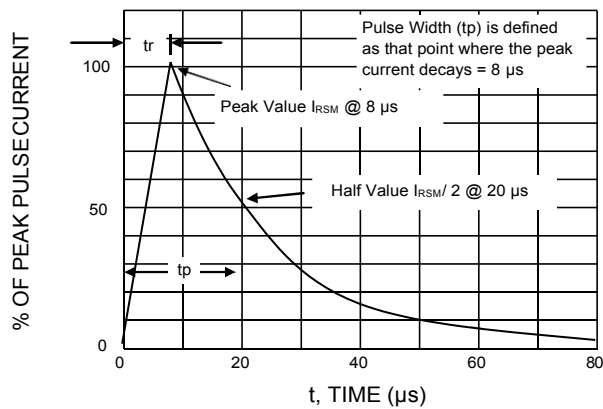
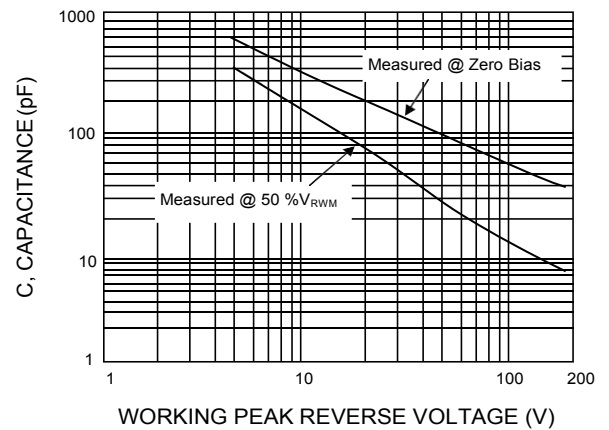


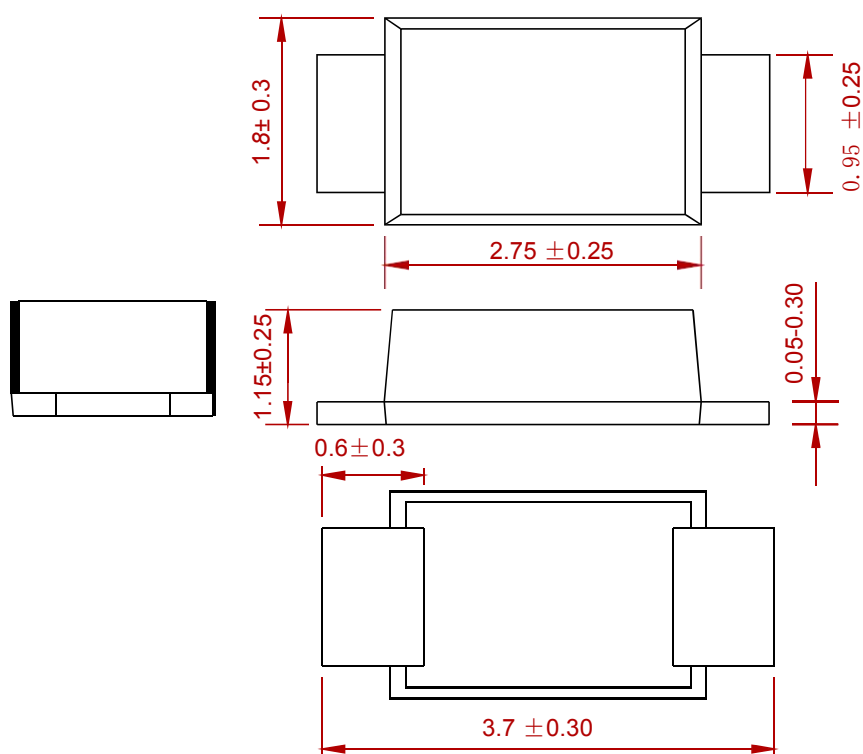
FIG.5 - 8 x 20 μs PULSE WAVEFORM



**FIG. 6 - CAPACITANCE VS. WORKING PEAK
REVERSE VOLTAGE**

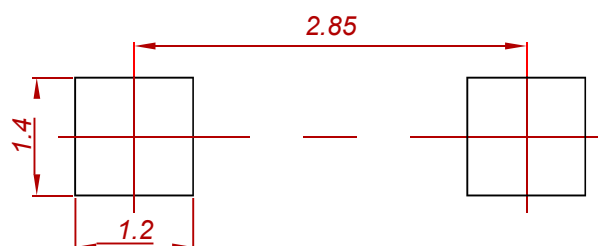


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PDCV300JB	SOD-123FL	3000

Attention

■ Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.

■ MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.

■ Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

■ MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

■ In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

■ No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.

■ Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.

■ Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.